

1.8V CONFIGURABLE BUFFER WITH ADDRESS-PARITY TEST

IDT74SSTU32866B

FEATURES:

- · 1.8V Operation
- · SSTL 18 style clock and data inputs
- · Differential CLK input
- · Configurable as 25-bit 1:1 or 14-bit 1:2 registered buffer
- Control inputs compatible with LVCMOS levels
- · Flow-through architecture for optimum PCB design
- Latch-up performance exceeds 100mA
- ESD >2000V per MIL-STD-883, Method 3015; >200V using machine model (C = 200pF, R = 0)
- · Checks parity on data inputs
- Available in 96-pin LFBGA package

APPLICATIONS:

- Along with CSPU877/A/D DDR2-400 PLL, provides complete solution for DDR2-400/533 DIMMs
- Optimized for DDR2-400/533 (PC2-3200/4300) JEDEC Raw Cards E, F, and G

DESCRIPTION:

This 25-bit 1:1/14-bit 1:2 configurable registered buffer is designed for 1.7V to 1.9V VDD operation. In the 1:1 pinout configuration, only one device per DIMM is required to drive nine SDRAM loads. In the 1:2 pinout configuration, two devices per DIMM are required to drive eighteen SDRAM loads. All inputs are SSTL_18, except reset (\overline{RESET}) and control (Cn) inputs, which are LVCMOS. All outputs are edge-controlled circuits optimized for unterminated DIMM loads, and meet SSTL_18 specifications, except the open-drain error (\overline{QERR}) output.

The SSTU32866B operates from a differential clock (CLK and $\overline{\text{CLK}}$). Data are registered at the crossing of CLK going high and $\overline{\text{CLK}}$ going low. Parity is checked on the parity bit (PAR_IN) input which arrives one cycle after the input data to which it applies. The $\overline{\text{QERR}}$ output is open drain.

When used as a single device, the C0 and C1 inputs are tied low. In this configuration, the partial-parity-out (PPO) and \overline{QERR} signals are produced two clock cycles after the corresponding data output.

When used in pairs, the C0 input of the first register is tied low and the C0 input of the second register is tied high. The C1 input of both registers are tied high. The \overline{QERR} output of the first SSTU32866B is left floating and the valid error information is latched on the \overline{QERR} output of the second SSTU32866B.

If an error occurs and the \overline{QERR} output is driven low, it stays latched low for two clock cycles or until \overline{RESET} is driven low. The DIMM-dependent signals (DODT, DCKE, \overline{DCS} , and \overline{CSR}) are not included in the parity check.

The CO input controls the pinout configuration of the 1:2 pinout from register A configuration (when low) to register B configuration (when high). The C1 input controls the pinout configurationfrom 25-bit 1:1 (when low) to 14-bit 1:2 (when high). C0 and C1 should not be switched during normal operation. They should be hard-wired to a valid low or high level to configure the register in the desired mode. In the 25-bit 1:1 pinout configuration, the A6, D6, and H6 terminals are driven low and should not be used.

The device supports low-power standby operation. When \overline{RESET} is low, the differential input recievers are disabled, and undriven (floating) data, clock, and reference voltage (VREF) inputs are allowed. In addition, when \overline{RESET} is low, all registers are reset and all outputs except \overline{QERR} are forced low. The LVCMOS \overline{RESET} and Cn inputs always must be held at a valid logic high or low level.

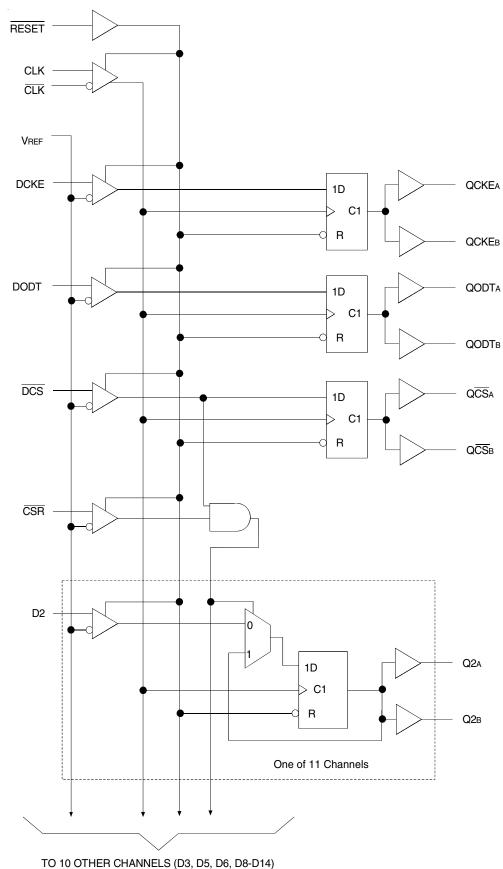
There are two VREF pins (A3 and T3). However, it is necessary to only connect one of the two VREF pins to the external VREF power supply. An unused VREF pin should be terminated with a VREF coupling capacitor.

The device also supports low-power active operation by monitoring both system chip select (\overline{DCS} and \overline{CSR}) inputs and will gate the Qn and PPO outputs from changing states when both \overline{DCS} and \overline{CSR} inputs are high. If either \overline{DCS} or \overline{CSR} input is low, the Qn and PPO outputs will function normally. Also, if the internal low power signal ($\overline{LPS1}$) is high, the device will gate the \overline{QERR} output from changing states. If $\overline{LPS1}$ is low, the \overline{QERR} output will function normally. The \overline{RESET} input has priority over the \overline{DCS} and \overline{CSR} control and when driven low will force the Qn and PPO outputs low, and the \overline{QERR} output high. If the \overline{DCS} control functionality is not desired, then the \overline{CSR} input can be hard-wired to ground, in which case the setuptime requirement for \overline{DCS} would be the same as for the other D data inputs. To control the low-power mode with \overline{DCS} only, then the \overline{CSR} input should be pulled up to VDD through a pullup resistor.

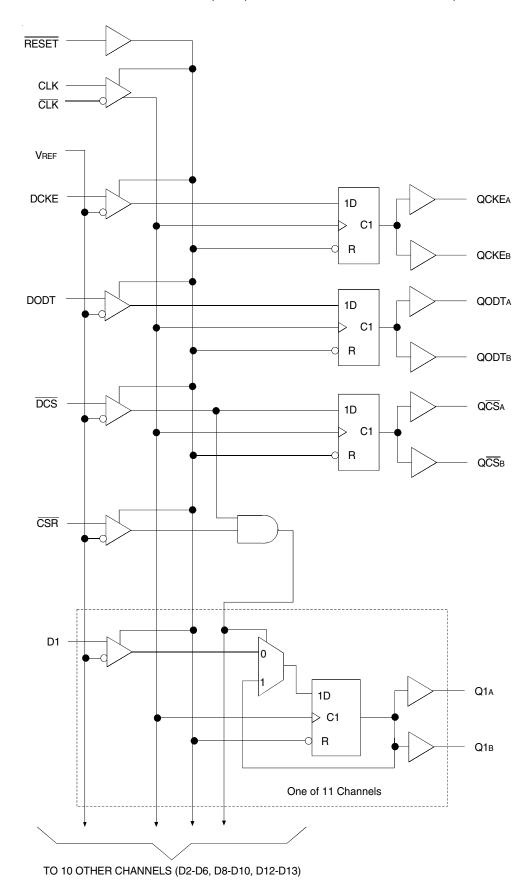
To ensure defined outputs from the register before a stable clock has been supplied, \overline{RESET} must be held in the low state during power up.

APRIL 2005

FUNCTIONAL BLOCK DIAGRAM (1:2) - A CONFIGURATION (POSITIVE LOGIC)



FUNCTIONAL BLOCK DIAGRAM (1:2) - B CONFIGURATION (POSITIVE LOGIC)



PIN CONFIGURATION (TYPE A)

6	QCKEB	Q2B	Q3B	QODTB	Q5B	Q6B	C0	QCSB	NC	Q8B	Q9B	Q10B	Q11B	Q12B	Q13B	Q14B
5	QCKEA	Q2A	Q3A	QODTA	Q5A	Q6A	C1	QCSA	NC	Q8A	Q9A	Q10A	Q11A	Q12A	Q13A	Q14A
4	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	VDD
3	VREF	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	VREF
2	PPO	DNU	DNU	QERR	DNU	DNU	RESET	DCS	CSR	DNU	DNU	DNU	DNU	DNU	DNU	DNU
1	DCKE	D2	D3	DODT	D5	D6	PAR_IN	CLK	CLK	D8	D9	D10	D11	D12	D13	D14
	A	В	С	D	E	F	G	Н	J	K	L	М	N	Р	R	T

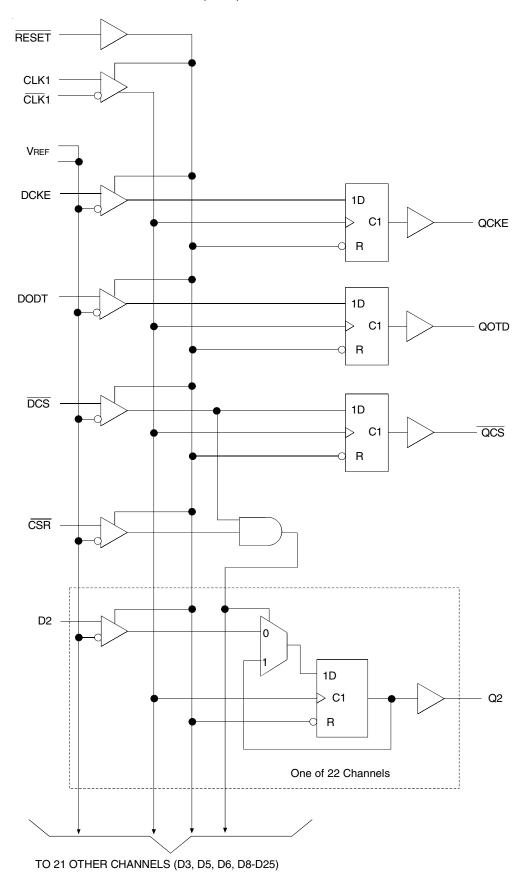
96-PIN LFBGA 1:2 REGISTER (TYPE A, FRONTSIDE) **TOP VIEW**

PIN CONFIGURATION (TYPE B)

6	Q1B	Q2B	Q3B	Q4B	Q5B	Q6B	C0	QCSB	NC	Q8B	Q9B	Q10B	QODTB	Q12B	Q13B	QCKEB
5	Q1A	Q2A	Q3A	Q4A	Q5A	Q6A	C1	QCSA	NC	Q8A	Q9A	Q10A	QODTA	Q12A	Q13A	QCKEA
4	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	VDD
3	VREF	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	VREF
2	PPO	DNU	DNU	QERR	DNU	DNU	RESET	DCS	CSR	DNU	DNU	DNU	DNU	DNU	DNU	DNU
1	D1	D2	D3	D4	D5	D6	PAR_IN	CLK	CLK	D8	D9	D10	DODT	D12	D13	DCKE
	A	В	С	D	E	F	G	Н	J	К	L	М	N	Р	R	т

96-PIN LFBGA 1:2 REGISTER (TYPE B, BACKSIDE) **TOP VIEW**

FUNCTIONAL BLOCK DIAGRAM (1:1)



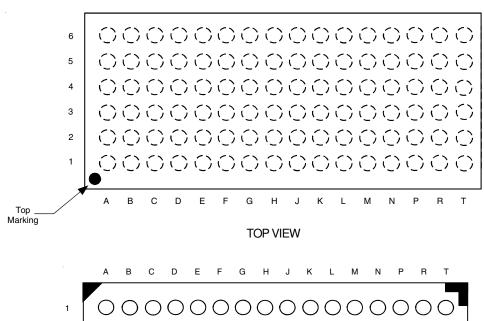
PIN CONFIGURATION

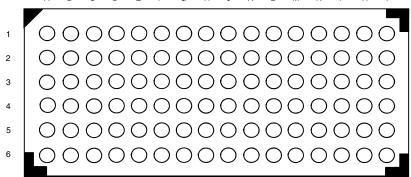
6	DNU	Q15	Q16	DNU	Q17	Q18	CO	DNU	NC	Q19	Q20	Q21	Q22	Q23	Q24	Q25
5	QCKE	Q2	Q3	QODT	Q5	Q6	C1	QCS	NC	Q8	Q9	Q10	Q11	Q12	Q13	Q14
4	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	VDD
3	VREF	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	GND	VDD	VREF
2	PPO	D15	D16	QERR	D17	D18	RESET	DCS	CSR	D19	D20	D21	D22	D23	D24	D25
1	DCKE	D2	D3	DODT	D5	D6	PAR_IN	CLK	CLK	D8	D9	D10	D11	D12	D13	D14
		В	С	D	E	F	G	Н	J	K	L	М	N	Р	R	Т

^{*}Rows 3 and 4 are reserved for VDD and GND.

96-PIN LFBGA 1:1 REGISTER TOP VIEW

96 BALL LFBGA PACKAGE ATTRIBUTES





BOTTOMVIEW SIDE VIEW

FUNCTION TABLE (EACH FLIP-FLOP) (1)

			Inputs			Qx	Q CS x	QODTx, QCKEx
RESET	DCS	CSR	CLK	CLK	Dx, DODT, DCKE	Outputs	Output	Outputs
Н	L	L	1	\downarrow	L	L	L	L
Н	L	L	↑	\downarrow	Н	Н	L	Н
Н	L	L	L or H	L or H	X	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾
Н	L	Н	↑	\downarrow	L	L	L	L
Н	L	Н	↑	\downarrow	Н	Н	L	Н
Н	L	Н	L or H	L or H	X	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾
Н	Н	L	↑	\downarrow	L	L	Н	L
Н	Н	L	↑	\downarrow	Н	Н	Н	Н
Н	Н	L	L or H	L or H	X	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾
Н	Н	Н	↑	\downarrow	Ļ	Q ₀ ⁽²⁾	Н	L
Н	Н	Н	↑	\downarrow	Н	Q ₀ ⁽²⁾	Н	Н
Н	Н	Н	L or H	L or H	X	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾	Q ₀ ⁽²⁾
L	X or Floating	L	L	L				

NOTES:

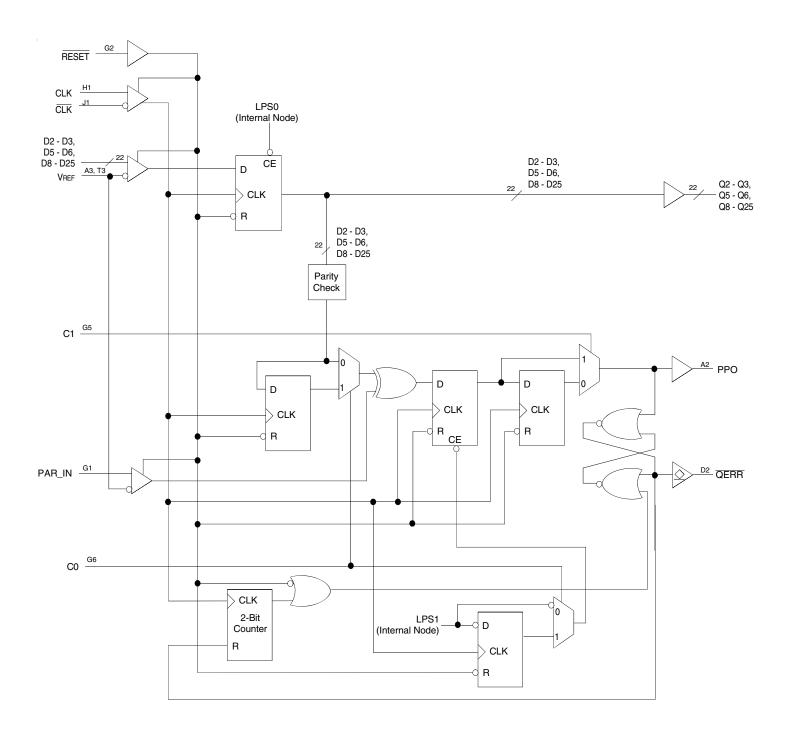
- 1. H = HIGH Voltage Level
 - L = LOW Voltage Level
 - X = Don't Care
 - 1 = LOW to HIGH
 - \downarrow = HIGH to LOW
- 2. Output level before the indicated steady-state conditions were established.

PARITY AND STANDBY FUNCTION TABLE(1)

			Inp	outs			Out	puts
RESET	DCS	CSR	CLK	CLK	Σ of Inputs = H (D1 - D25)	PAR_IN ⁽²⁾	PPO ⁽³⁾	QERR(4)
Н	L	Х	1	\downarrow	Even	L	L	Н
Н	L	Х	1	\downarrow	Odd	L	Н	L
Н	L	Х	1	\downarrow	Even	Н	Н	L
Н	L	Х	1	\downarrow	Odd	Н	L	Н
Н	Н	L	↑	\downarrow	Even	L	L	Н
Н	Н	L	↑	\downarrow	Odd	L	Н	L
Н	Н	L	↑	\downarrow	Even	Н	Н	L
Н	Н	L	↑	\downarrow	Odd	Н	L	Н
Н	Н	Н	↑	\downarrow	X	Х	PPO ₀	$\overline{QERR}_{\scriptscriptstyle{0}}$
Н	Х	Х	L or H	L or H	X	Х	PPO ₀	$\overline{QERR}_{\scriptscriptstyle{0}}$
L	X or Floating	X or Floating	X or Floating	X or Floating	XorFloating	X or Floating	L	Н

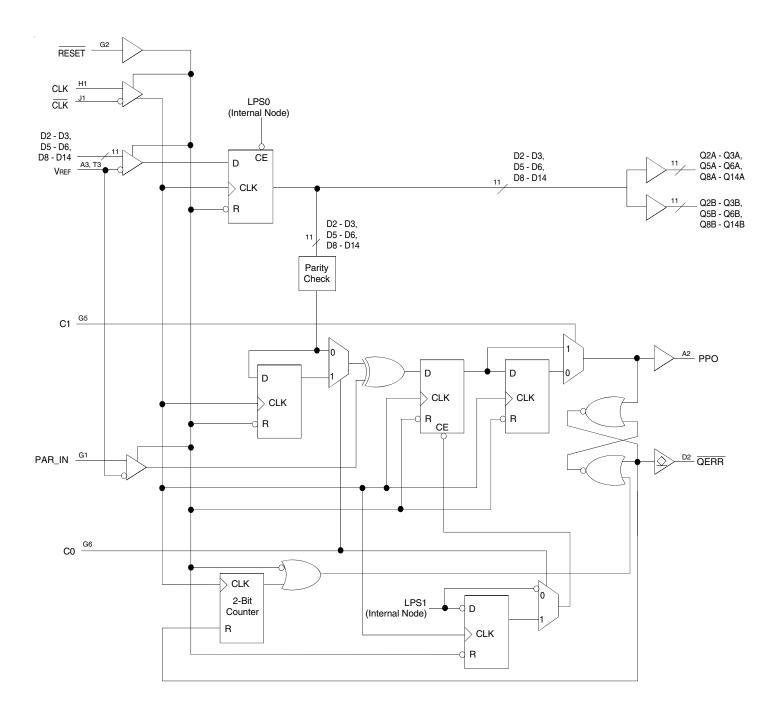
- 1. H = HIGH Voltage Level
 - L = LOW Voltage Level
 - X = Don't Care
 - ↑ = LOW to HIGH
 - \downarrow = HIGH to LOW
- 2. Data Inputs = D2, D3, D5, D6, D8 D25 when C0 = 0 and C1 = 0.
 - Data Inputs = D2, D3, D5, D6, D8 D14 when C0 = 0 and C1 = 1.
 - Data Inputs = D1 D6, D8 D10, D12, D13 when C0 = 1 and C1 = 1.
- 3. PAR_IN arrives one clock cycle (C0 = 0), or two clock cycles (C0 = 1), after the data to which it applies.
- 4. This transition assumes QERR is HIGH at the crossing of CLK going HIGH and CLK going LOW. If QERR is LOW, it stays latched LOW for two clock cycles or until RESET is driven LOW.

LOGIC DIAGRAM (1:1)



Parity Logic Diagram for 1:1 Register - A Configuration (Positive Logic); C0 = 0, C1 = 0

LOGIC DIAGRAM (1:2)



Parity Logic Diagram for 1:2 Register - A Configuration (Positive Logic); C0 = 0, C1 = 1

ABSOLUTE MAXIMUM RATINGS (1)

Symbol	Description		Max.	Unit
VDD	Supply Voltage Range		-0.5 to 2.5	V
VI ^(2,3)	Input Voltage Range		-0.5 to 2.5	V
Vo ^(2,3)	Output Voltage Range		-0.5 to VDD +0.5	V
lıĸ	Input Clamp Current	VI < 0	±50	mA
		VI > VDD		
Іок	Output Clamp Current	Vo < 0	±50	mA
		Vo > VDD		
lo	Continuous Output Curr	rent,	±50	mA
	Vo = 0 to VDD			
VDD	Continuous Current through each		±100	mA
	VDD or GND			
Tstg	Storage Temperature Ra	ange	-65 to +150	°C

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. The input and output negative voltage ratings may be exceeded if the ratings of the I/P and O/P clamp current are observed.
- 3. This value is limited to 2.5V maximum.

MODE SELECT

C ₀	C1	Device Mode
0	0	1:1 25-bit to 25-bit
0	1	1:214-bit to 28-bit, Front (Type A)
1	0	Reserved
1	1	1:214-bit to 28-bit, Back (Type B)

TERMINAL FUNCTIONS (ALL PINS)

Terminal	Electrical	
Name	Characteristics	Description
GND	Ground Input	Ground
V _{DD}	1.8V nominal	Power Supply Voltage
VREF	0.9V nominal	Input Reference Voltage
CLK	Differential Input	Positive Master Clock Input
CLK	Differential Input	Negative Master Clock Input
Сx	LVCMOS Input	Configuration Control Inputs
RESET	LVCMOS Input	Asynchronous Reset Input. Resets registers and disables VREF data and clock differential-input receivers.
$\overline{\text{CSR}}$, $\overline{\text{DCS}}$	SSTL_18Input	Chip Select Inputs. Disables outputs Dx switching when both inputs are HIGH.
Dx	SSTL_18Input	Data Input. Clocked in on the crossing of the rising edge of CLK and the falling edge of $\overline{\text{CLK}}$.
DODT	SSTL_18 Input	The outputs of this register bit will not be suspended by the \overline{DCS} and \overline{CSR} controls
DCKE	SSTL_18Input	The outputs of this register bit will not be suspended by the \overline{DCS} and \overline{CSR} controls
Qx	1.8V CMOS	Data Outputs that are suspended by the $\overline{ m DCS}$ and $\overline{ m CSR}$ controls
QCSx	1.8V CMOS	Data Output that will not be suspended by the $\overline{ m DCS}$ and $\overline{ m CSR}$ controls
QODTx	1.8V CMOS	Data Output that will not be suspended by the $\overline{ m DCS}$ and $\overline{ m CSR}$ controls
QCKEx	1.8V CMOS	Data Output that will not be suspended by the DCS and CSR controls
PAR_IN	SSTL_18Input	Parity Input. Clocked on the rising edge of CLK one cycle after corresponding data input.
QERR	Open Drain Output	Output Error bit, generated one cycle after the corresponding data output
PPO	1.8V CMOS	Partial Parity Output. Indicates ODD parity of Data Inputs and Parity In.

OPERATING CHARACTERISTICS, TA = 25°C (1,2)

Symbol	Parameter		Min.	Тур.	Max.	Unit
VDD	Supply Voltage		1.7	_	1.9	V
VREF	Reference Voltage		0.49 * VDD	0.5 * VDD	0.51 * VDD	V
VTT	Termination Voltage		VREF-40mV	VREF	VREF+ 40mV	V
Vı	Input Voltage		0	_	VDD	V
VIH	AC High-Level Input Voltage		VREF+ 250mV	_	_	
VIL	AC Low-Level Input Voltage	Data Inputs, $\overline{\text{CSR}}$, $\overline{\text{DCS}}$,	_	_	VREF-250mV	V
VIH	DC High-Level Input Voltage	PAR_IN	VREF+ 125mV			
VIL	DC Low-Level Input Voltage			_	VREF-125mV	
VIH	High-Level Input Voltage	RESET, Cx	0.65 * VDD		1	٧
VIL	Low-Level Input Voltage	RESET, Cx			0.35 * VDD	V
Vicr	Common Mode Input Voltage	CLK, CLK	0.675	_	1.125	V
VID	Differential Input Voltage	CLK, CLK	600	_	_	mV
Іон	High-Level Output Current	Data Outputs, PPO	_	_	-8	mA
lol	Low-Level Output Current Data Outputs, PPO, QERR		_	_	8	
TA	Operating Free-Air Temperature)	0	_	70	°C

NOTES:

- 1. The RESET and Cx inputs of the device must be held at valid levels (not floating) to ensure proper device operation.
- 2. The differential inputs must not be floating unless $\overline{\text{RESET}}$ is LOW.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: $TA = 0^{\circ}C$ to $+70^{\circ}C$, $VDD = 1.8V \pm 0.1V$

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
Vон	Output HIGH Voltage	IOH = -6 mA		1.2	_	_	٧
Vol	Output LOW Voltage	IoL = 6 mA		_	_	0.5	٧
lı	All Inputs ⁽¹⁾	VI = VDD or GND	_	_	±5	μΑ	
IDD	Static Standby	Io = 0, VDD = 1.9V, RESET = GND		_	_	100	μΑ
	Static Operating	Io = 0, VDD = 1.9V, \overline{RESET} = VDD, VI = VIH (AC) or V	IL (AC)	_	_	40	mA
IDDD	Dynamic Operating	$IO = 0$, $VDD = 1.8V$, $\overline{RESET} = VDD$, $VI = VIH (AC)$ or V	$IO = 0$, $VDD = 1.8V$, $\overline{RESET} = VDD$, $VI = VIH$ (AC) or VIL (AC),		_	_	μΑ/Clock
	(Clock Only)	CLK and $\overline{\text{CLK}}$ Switching 50% Duty Cycle.					MHz
		$IO = 0$, $VDD = 1.8V$, $\overline{RESET} = VDD$,	1:1 Mode	_	_	_	
	Dynamic Operating	$VI = VIH (AC) \text{ or } VIL (AC), CLK \text{ and } \overline{CLK} \text{ Switching at }$					μΑ/Clock
	(Per Each Data Input)	50% Duty Cycle. One Data Input Switching at	1:2 Mode	–	_	_	MHz/Data
		Half Clock Frequency, 50% Duty Cycle.					Input
	Data Inputs, CSR, PAR_IN		_	2.5	_	3.5	
Сі	CI CLK and CLK VICR = 0.9V, VID = 600mV		2	_	3	рF	
	RESET	VI = VDD or GND		_	_	_	

NOTE:

1. Each V_{REF} pin (A3, T3) should be tested independently, with the other pin open circuit.

TIMING REQUIREMENTS OVER RECOMMENDED OPERATING FREE-AIR TEMPERATURE RANGE

			VDD = 1.8	V ± 0.1V	
Symbol	Parameter		Min.	Max.	Unit
fCLOCK	Clock Frequenc	су	_	270	MHz
tw	Pulse Duration	, CLK, CLK HIGH or LOW	1	_	ns
tact ^(1,2)	Differential Inpu	ts Active Time	_	10	ns
tinact ^(1,3)	Differential Inpu	ts Inactive Time	-	15	ns
		$\overline{\text{DCS}}$ before CLK \uparrow , $\overline{\text{CLK}}\downarrow$, $\overline{\text{CSR}}$ HIGH; $\overline{\text{CSR}}$ before CLK \uparrow , $\overline{\text{CLK}}\downarrow$, $\overline{\text{DCS}}$ HIGH	0.7		
tsu	SetupTime	DCS before CLK↑, CLK↓, CSR LOW	0.5	_	ns
		DODT, DCKE, and data before CLK \uparrow , $\overline{\text{CLK}} \downarrow$	0.5	_	
		PAR_IN before CLK↑, CLK↓	0.5	_	
tH	Hold Time	$\overline{ extsf{DCS}}$, DODT, DCKE, and data after CLK \uparrow , $\overline{ extsf{CLK}} \downarrow$	0.5	_	ns
		PAR_IN after CLK↑, CLK↓	0.5	_	

NOTES:

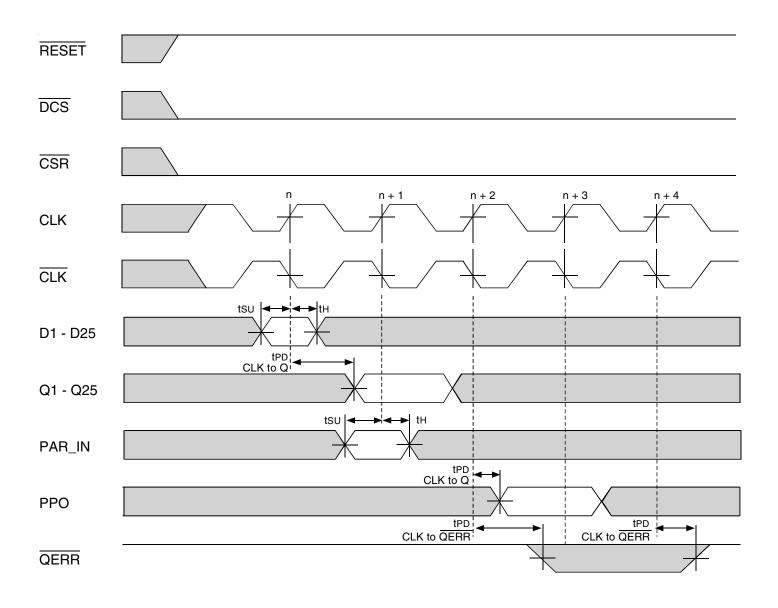
- 1. This parameter is not production tested.
- 2. Data and VREF inputs must be low a minimum time of tact max, after $\overline{\text{RESET}}$ is taken HIGH.
- 3. Data, VREF, and clock inputs must be held at valid levels (not floating) a minimum time of tINACT max, after RESET is taken LOW.

SWITCHING CHARACTERISTICS OVER RECOMMENDED FREE-AIR OPERATING RANGE (UNLESS OTHERWISE NOTED) (1)

	ON LLOG OTTILITION OF ITS	· = - <i>,</i>		
		V _{DD} = 1	.8V ± 0.1V	
Symbol	Parameter	Min	Max.	Unit
fMAX		270	_	MHz
tPDM ⁽²⁾	CLK and CLK to Q	1.41	2.15	ns
tPDMSS ^(2,3)	CLK and $\overline{\text{CLK}}$ to Q (simultaneous switching)	_	2.35	ns
trphl	RESET to Q	_	3	ns
dV/dt_r	Output slew rate from 20% to 80%	1	4	V/ns
dV/dt_f	Output slew rate from 20% to 80%	1	4	V/ns
dV/dt $_\Delta^{(4)}$	Output slew rate from 20% to 80%	_	1	V/ns
tPD .	CLK and CLK to PPO	0.5 ⁽⁵⁾	1.8 ⁽⁵⁾	ns
tPLH	CLK and CLK to QERR	1.2 ⁽⁵⁾	3 ⁽⁵⁾	ns
tPHL .	CLK and CLK to QERR	1 ⁽⁵⁾	2.4 ⁽⁵⁾	ns
trphl	RESET to PPO	_	3	ns
trplh	RESET to QERR	_	3	ns

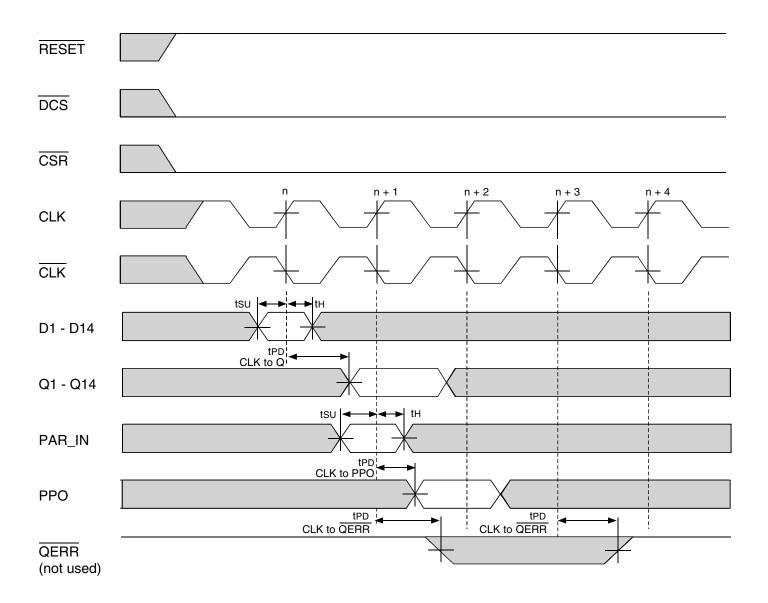
- 1. See TEST CIRCUITS AND WAVEFORMS.
- 2. Includes 350ps of test load transmission line delay.
- 3. This parameter is not production tested.
- 4. Difference between dV/dt_r (rising edge rate) and $\,dV/dt_f$ (falling edge rate).
- 5. For reference only. Final values to be determined.

REGISTER TIMING



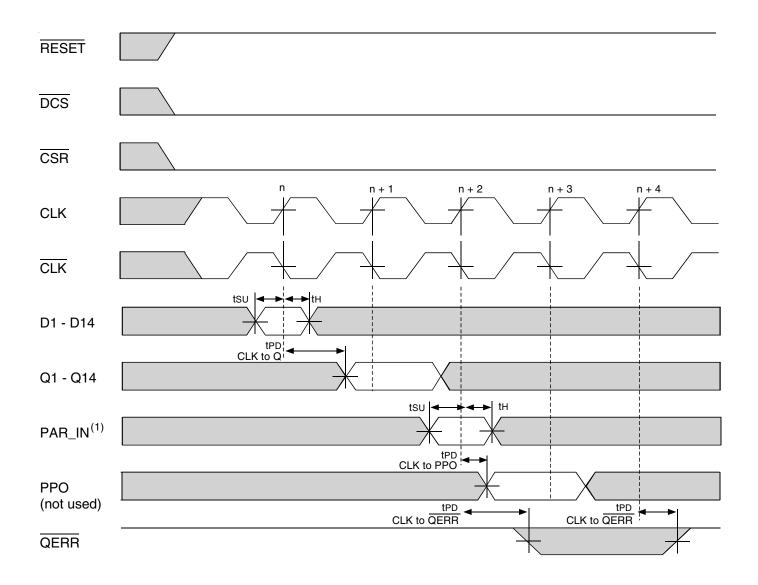
Timing Diagram for SSTU32866B Used as a Single Device; C0 = 0, C1 = 0

REGISTER TIMING



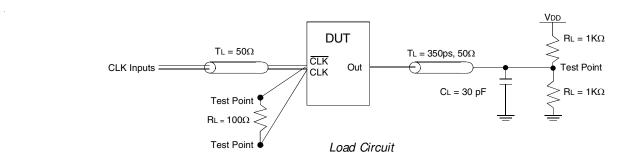
Timing Diagram for the First SSTU32866B (1:2 Register-A Configuration) Device Used in a Pair; C0 = 0, C1 = 1

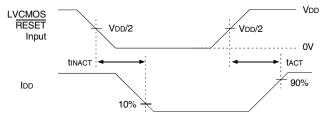
REGISTER TIMING



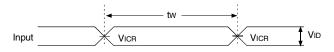
Timing Diagram for the First SSTU32866B (1:2 Register-B Configuration) Device Used in a Pair; C0 = 1, C1 = 1

TEST CIRCUITS AND WAVEFORMS (VDD = 1.8V ± 0.1V)

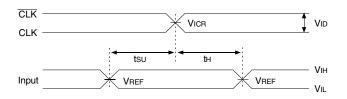




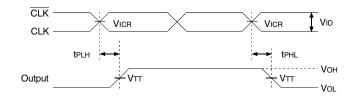
Voltage and Current Waveforms Inputs Active and Inactive Times



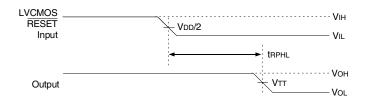
Voltage Waveforms - Pulse Duration



Voltage Waveforms - Setup and Hold Times



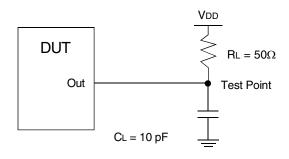
Voltage Waveforms - Propagation Delay Times



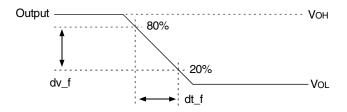
Voltage Waveforms - Propagation Delay Times

- 1. CL includes probe and jig capacitance.
- 2. IDD tested with clock and data inputs held at VDD or GND, and Io = 0mA
- 3. All input pulses are supplied by generators having the following characteristics: PRR \leq 10MHz, Zo = 50Ω , input slew rate = 1 V/ns \pm 20% (unless otherwise specified).
- 4. The outputs are measured one at a time with one transition per measurement.
- 5. VTT = VREF = VDD/2
- 6. VIH = VREF + 250mV (AC voltage levels) for differential inputs. VIH = VDD for LVCMOS input.
- 7. VIL = VREF 250mV (AC voltage levels) for differential inputs. VIL = GND for LVCMOS input.
- 8. VID = 600mV.
- 9. tPLH and tPHL are the same as tPDM.

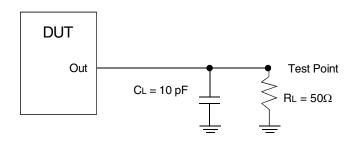
TEST CIRCUITS AND WAVEFORMS (VDD = 1.8V ± 0.1V)



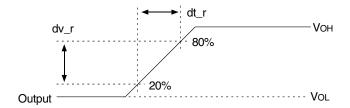
Load Circuit - High-to-Low Slew-Rate Adjustment



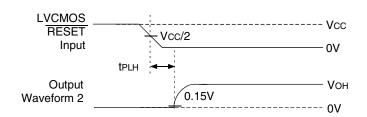
Voltage Waveforms - High-to-Low Slew-Rate Adjustment



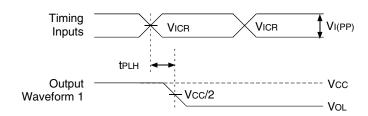
Load Circuit - Low-to-High Slew-Rate Adjustment



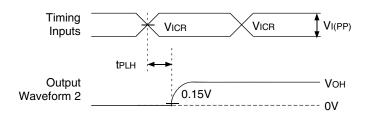
Voltage Waveforms - Low-to-High Slew-Rate Adjustment



Voltage Waveforms - Open Drain Low-to-High Transition Time, Reset



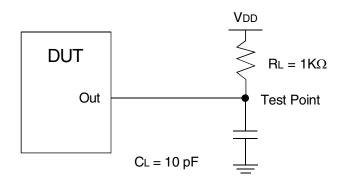
Voltage Waveforms - Open Drain Hight-to-Low Transition Time, Clock



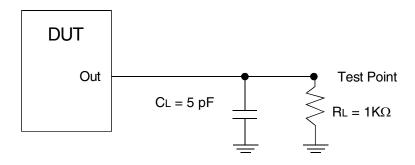
Voltage Waveforms - Open Drain Low-to-High Transition Time, Clock

- 1. CL includes probe and jig capacitance.
- 2. All input pulses are supplied by generators having the following characteristics: PRR \leq 10MHz, Zo = 50 Ω , input slew rate = 1 V/ns \pm 20% (unless otherwise specified).

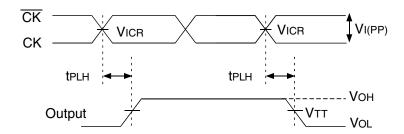
TEST CIRCUITS AND WAVEFORMS (VDD = 1.8V ± 0.1V)



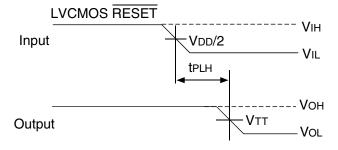
Load Circuit - QERR Output



Load Circuit - Partial-Parity-Out Load Circuit

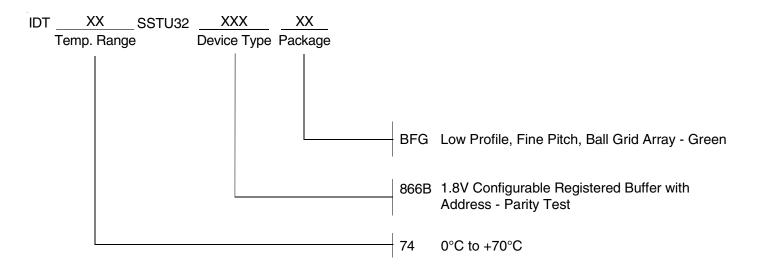


Voltage Waveforms - Propagation Delay Times with Respect to Clock Inputs



Voltage Waveforms - Propagation Delay Times with Respect to Reset Inputs

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